

## General Description

The CLC1003 is a single channel, high-performance, voltage feedback amplifier with near precision performance, low input voltage noise, and ultra low distortion. The CLC1003 offers 1mV maximum input offset voltage, 3.5nV/ $\sqrt{\text{Hz}}$  broadband input voltage noise, and 0.00005% THD at 1kHz. These amplifiers also provide 55MHz gain bandwidth product and 12V/ $\mu\text{s}$  slew rate making them well suited for applications requiring precision DC performance and high AC performance. This high-performance amplifier also offers a rail-to-rail input and output, simplifying single supply designs and offering larger dynamic range possibilities. The inputs extend beyond the rails by 500mV.

The CLC1003 is designed to operate from 2.5V to 12V supplies and operate over the extended temperature range of -40°C to +125°.

## FEATURES

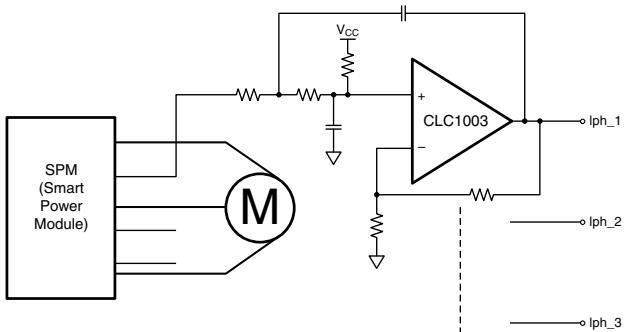
- 1mV maximum input offset voltage
- 0.00005% THD at 1kHz
- 5.3nV/ $\sqrt{\text{Hz}}$  input voltage noise > 10kHz
- -90dB/-85dB HD2/HD3 at 100kHz,  $R_L = 100\Omega$
- <-100dB HD2 and HD3 at 10kHz,  $R_L = 1\text{k}\Omega$
- Rail-to-rail input and output
- 55MHz unity gain bandwidth
- 12V/ $\mu\text{s}$  slew rate
- +80mA, -55mA output current
- -40°C to +125°C operating temperature range
- Fully specified at 3 and  $\pm 5\text{V}$  supplies
- CLC1003: ROHS compliant TSOT-5, SOIC-8 package options

## APPLICATIONS

- Active filters
- Sensor interface
- High-speed transducer amp
- Medical instrumentation
- Probe equipment
- Test equipment
- Smoke detectors
- Hand-held analytic instruments
- Current sense applications

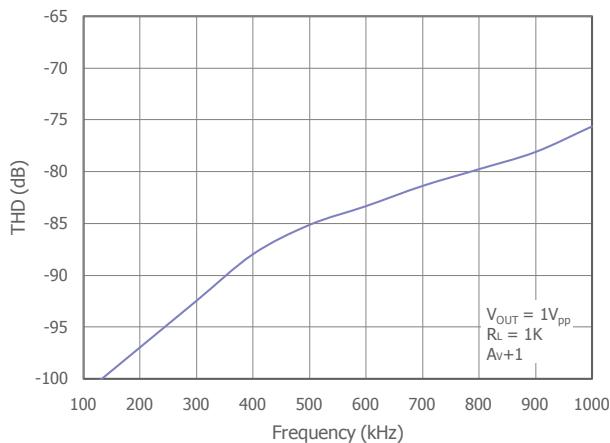
Ordering Information - [back page](#)

## Typical Application



Current Sensing in 3-Phase Motor

## THD vs. Frequency



## Absolute Maximum Ratings

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

$V_S$  ..... 0V to +14V  
 $V_{IN}$  .....  $-V_S - 0.5V$  to  $+V_S + 0.5V$

## Operating Conditions

Supply Voltage Range ..... 2.5V to 12V  
Operating Temperature Range ..... -40°C to 125°C  
Junction Temperature ..... 150°C  
Storage Temperature Range ..... -65°C to 150°C  
Lead Temperature (Soldering, 10s) ..... 260°C

## Package Thermal Resistance

$\theta_{JA}$  (TSOT-5) ..... 215°C/W

$\theta_{JA}$  (SOIC-8) ..... 150°C/W

Package thermal resistance ( $\theta_{JA}$ ), JEDEC standard, multi-layer test boards, still air.

## Electrical Characteristics at +3V

 $T_A = 25^\circ\text{C}$ ,  $V_S = +3\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$  to  $V_S/2$ ;  $G = 2$ ; unless otherwise noted.

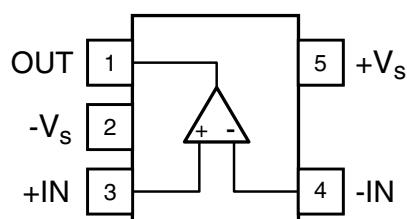
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Frequency Domain Response						
GBWP	-3dB Gain Bandwidth Product	$G = 10$ , $V_{\text{OUT}} = 0.05\text{V}_{\text{pp}}$		31		MHz
UGBW	Unity Gain Bandwidth	$V_{\text{OUT}} = 0.05\text{V}_{\text{pp}}$ , $R_f = 0$		50		MHz
BW <sub>SS</sub>	-3dB Bandwidth	$V_{\text{OUT}} = 0.05\text{V}_{\text{pp}}$		24		MHz
BW <sub>LS</sub>	Large Signal Bandwidth	$V_{\text{OUT}} = 2\text{V}_{\text{pp}}$		3.3		MHz
Time Domain						
$t_R$ , $t_F$	Rise and Fall Time	$V_{\text{OUT}} = 2\text{V}$ step; (10% to 90%)		150		ns
$t_S$	Settling Time to 0.1%	$V_{\text{OUT}} = 2\text{V}$ step		78		ns
OS	Overshoot	$V_{\text{OUT}} = 2\text{V}$ step		0.3		%
SR	Slew Rate	2V step		11		$\text{V}/\mu\text{s}$
Distortion/Noise Response						
HD2	2nd Harmonic Distortion	$2\text{V}_{\text{pp}}$ , 10kHz, $R_L = 1\text{k}\Omega$		-98		dBc
		$2\text{V}_{\text{pp}}$ , 100kHz, $R_L = 100\Omega$		-85		dBc
HD3	3rd Harmonic Distortion	$2\text{V}_{\text{pp}}$ , 10kHz, $R_L = 1\text{k}\Omega$		-95		dBc
		$2\text{V}_{\text{pp}}$ , 100kHz, $R_L = 100\Omega$		-81		dBc
THD	Total Harmonic Distortion	$1\text{V}_{\text{pp}}$ , 1kHz, $G = 1$ , $R_L = 2\text{k}\Omega$		0.0005		%
$e_n$	Input Voltage Noise	>10kHz		5.5		$\text{nV}/\sqrt{\text{Hz}}$
		>100kHz		3.9		$\text{nV}/\sqrt{\text{Hz}}$
DC Performance						
$V_{\text{IO}}$	Input Offset Voltage			0.088		mV
$dV_{\text{IO}}$	Average Drift			1.3		$\mu\text{V}/^\circ\text{C}$
$I_B$	Input Bias Current			-0.340		$\mu\text{A}$
$dI_B$	Average Drift			0.8		$\text{nA}/^\circ\text{C}$
$I_{\text{OS}}$	Input Offset Current			0.2		$\mu\text{A}$
PSRR	Power Supply Rejection Ratio	DC		100		dB
$A_{\text{OL}}$	Open Loop Gain	$V_{\text{OUT}} = V_S/2$		104		dB
$I_S$	Supply Current	per channel		1.85		mA
Input Characteristics						
$R_{\text{IN}}$	Input Resistance	Non-inverting, $G = 1$		30		$\text{M}\Omega$
$C_{\text{IN}}$	Input Capacitance			1.1		pF
CMIR	Common Mode Input Range			-0.5 to 3.5		V
CMRR	Common Mode Rejection Ratio	DC, $V_{\text{CM}} = 0.5\text{V}$ to $2.5\text{V}$		94		dB
Output Characteristics						
$V_{\text{OUT}}$	Output Swing	$R_L = 150\Omega$		0.085 to 2.80		V
		$R_L = 1\text{k}\Omega$		0.04 to 2.91		V
$I_{\text{OUT}}$	Output Current			+75, -40		mA
$I_{\text{sc}}$	Short Circuit Current	$V_{\text{OUT}} = V_S/2$		+95, -50		mA

Electrical Characteristics at  $\pm 5V$  $T_A = 25^\circ C$ ,  $V_S = \pm 5V$ ,  $R_f = 1k\Omega$ ,  $R_L = 1k\Omega$  to GND;  $G = 2$ ; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Frequency Domain Response						
GBWP	-3dB Gain Bandwidth Product	$G = 10$ , $V_{OUT} = 0.05V_{pp}$		35		MHz
UGBW	Unity Gain Bandwidth	$V_{OUT} = 0.05V_{pp}$ , $R_f = 0$		55		MHz
BW <sub>SS</sub>	-3dB Bandwidth	$V_{OUT} = 0.05V_{pp}$		25		MHz
BW <sub>LS</sub>	Large Signal Bandwidth	$V_{OUT} = 2V_{pp}$		3.6		MHz
Time Domain						
$t_R$ , $t_F$	Rise and Fall Time	$V_{OUT} = 2V$ step; (10% to 90%)		125		ns
$t_S$	Settling Time to 0.1%	$V_{OUT} = 2V$ step		80		ns
OS	Overshoot	$V_{OUT} = 2V$ step		0.3		%
SR	Slew Rate	4V step		12		V/ $\mu$ s
Distortion/Noise Response						
HD2	2nd Harmonic Distortion	$2V_{pp}$ , 10kHz, $R_L = 1k\Omega$		-125		dBc
		$2V_{pp}$ , 100kHz, $R_L = 100\Omega$		-90		dBc
HD3	3rd Harmonic Distortion	$2V_{pp}$ , 10kHz, $R_L = 1k\Omega$		-127		dBc
		$2V_{pp}$ , 100kHz, $R_L = 100\Omega$		-85		dBc
THD	Total Harmonic Distortion	$1V_{pp}$ , 1kHz, $G = 1$ , $R_L = 2k\Omega$		0.00005		%
$e_n$	Input Voltage Noise	>10kHz		5.3		nV/ $\sqrt{Hz}$
		>100kHz		3.5		nV/ $\sqrt{Hz}$
DC Performance						
$V_{IO}$	Input Offset Voltage		-1	0.050	1	mV
$dV_{IO}$	Average Drift			1.3		$\mu$ V/ $^\circ$ C
$I_B$	Input Bias Current		-2.6	-0.30	2.6	$\mu$ A
$dI_B$	Average Drift			0.85		nA/ $^\circ$ C
$I_{OS}$	Input Offset Current			0.2	0.7	$\mu$ A
PSRR	Power Supply Rejection Ratio	DC	82	100		dB
$A_{OL}$	Open Loop Gain	$V_{OUT} = V_S / 2$	95	115		dB
$I_S$	Supply Current	per channel		2.2	2.75	mA
Input Characteristics						
$R_{IN}$	Input Resistance	Non-inverting, $G = 1$		30		M $\Omega$
$C_{IN}$	Input Capacitance			1		pF
CMIR	Common Mode Input Range			$\pm 5.5$		V
CMRR	Common Mode Rejection Ratio	DC, $V_{CM} = -3V$ to $3V$	70	95		dB
Output Characteristics						
$V_{OUT}$	Output Swing	$R_L = 150\Omega$		-4.826 to 4.534		V
		$R_L = 1k\Omega$	-4.7	-4.93 to 4.85	4.7	V
$I_{OUT}$	Output Current			+80, -55		mA
$I_{SC}$	Short Circuit Current	$V_{OUT} = V_S / 2$		+115, -90		mA

## CLC1003 Pin Configurations

## TSOT-5

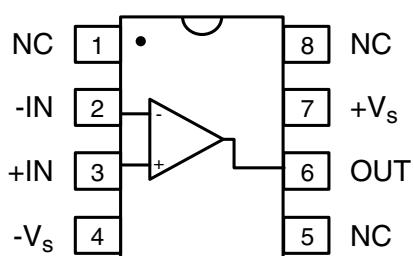


## CLC1003 Pin Assignments

## TSOT-5

Pin No.	Pin Name	Description
1	OUT	Output
2	-V <sub>S</sub>	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	+V <sub>S</sub>	Positive supply

## SOIC-8



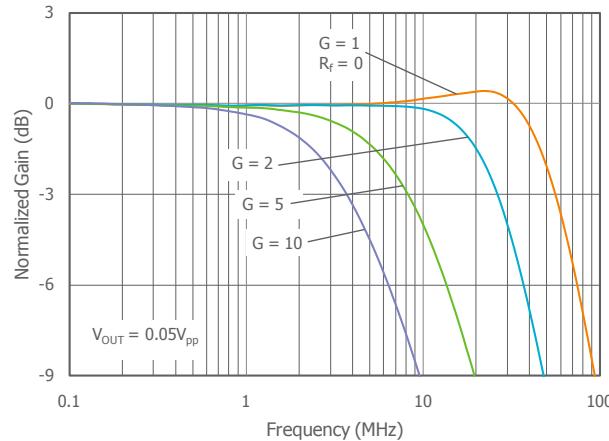
## SOIC-8

Pin No.	Pin Name	Description
1	NC	No Connect
2	-IN	Negative input
3	+IN	Positive input
4	-V <sub>S</sub>	Negative supply
5	NC	No Connect
6	OUT	Output
7	+V <sub>S</sub>	Positive supply
8	NC	No Connect

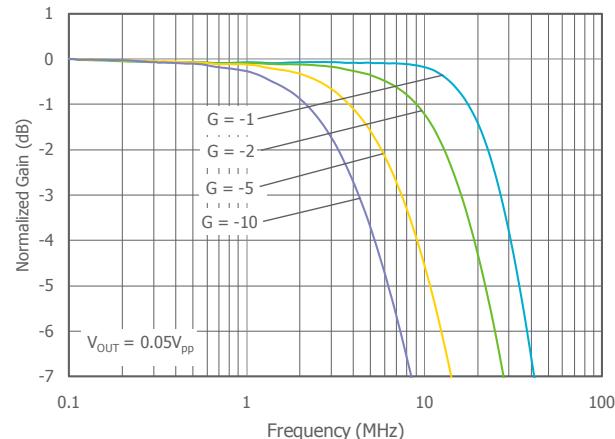
## Typical Performance Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$ ,  $G = 2$ ; unless otherwise noted.

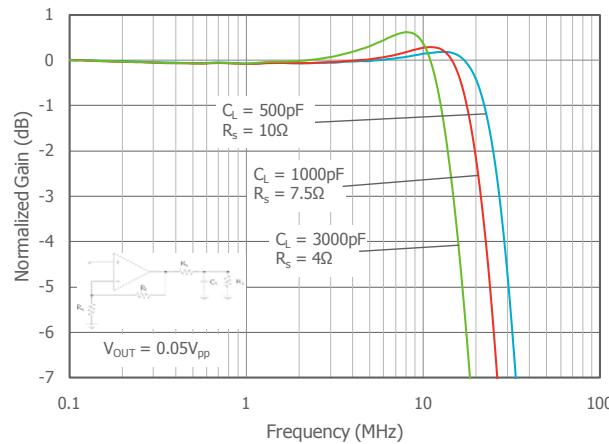
Non-Inverting Frequency Response



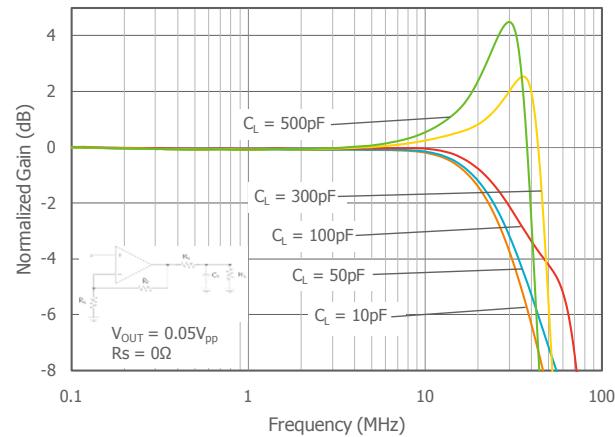
Inverting Frequency Response



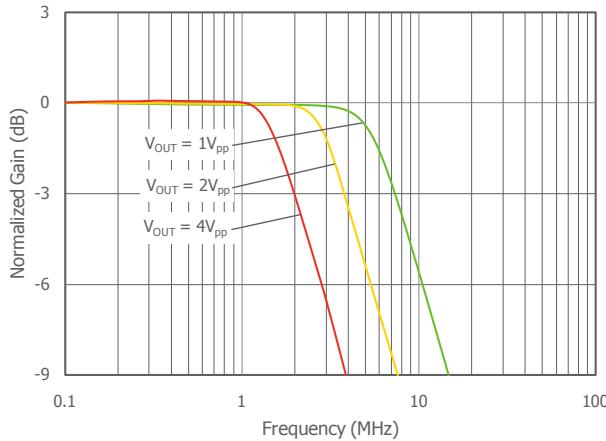
Frequency Response vs.  $C_L$



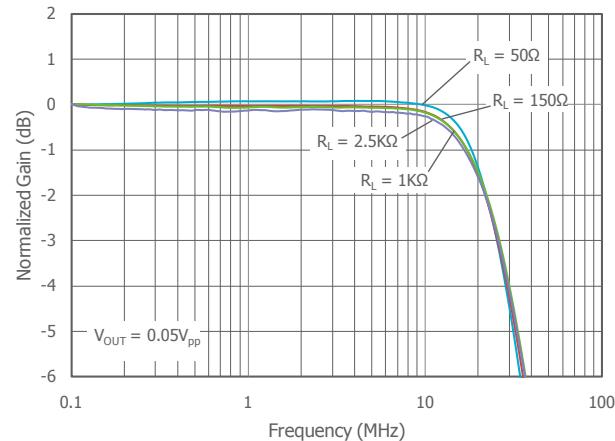
Frequency Response vs.  $C_L$  without  $R_S$



Frequency Response vs.  $V_{\text{OUT}}$



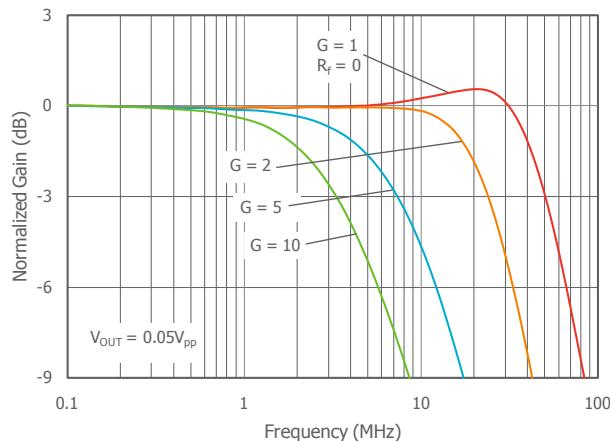
Frequency Response vs.  $R_L$



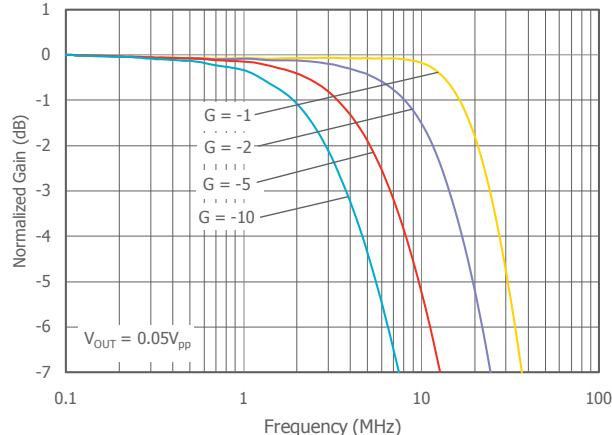
## Typical Performance Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$ ,  $G = 2$ ; unless otherwise noted.

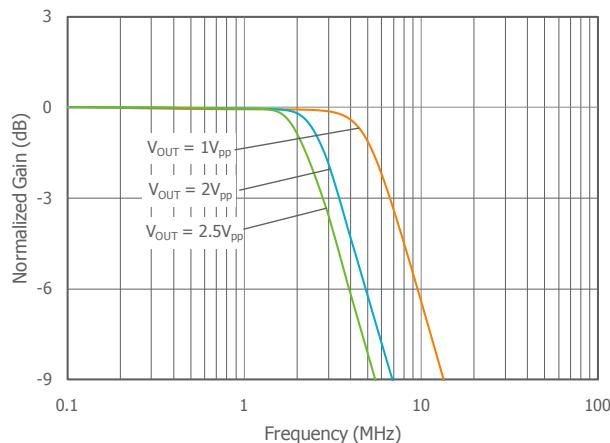
Non-Inverting Frequency Response at  $V_S = 3\text{V}$



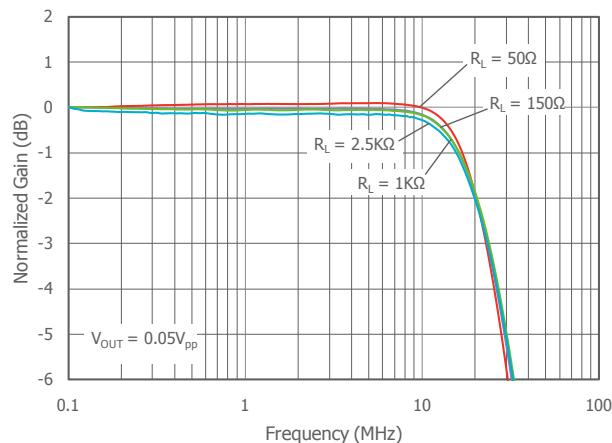
Inverting Frequency Response at  $V_S = 3\text{V}$



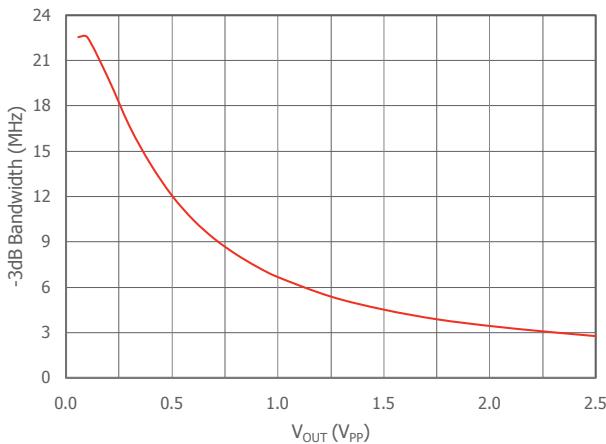
Frequency Response vs.  $V_{\text{OUT}}$  at  $V_S = 3\text{V}$



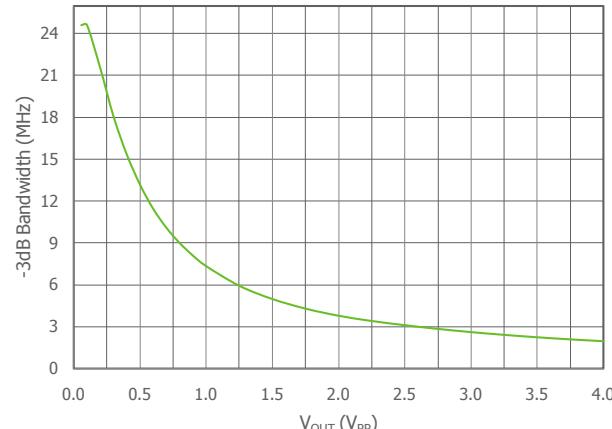
Frequency Response vs.  $R_L$  at  $V_S = 3\text{V}$



-3dB Bandwidth vs. Output Voltage at  $V_S = 3\text{V}$



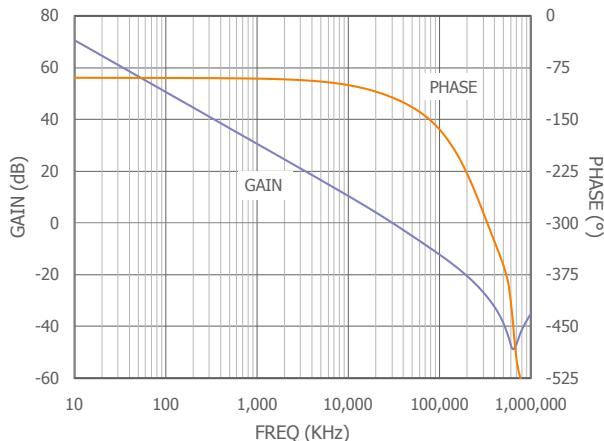
-3dB Bandwidth vs. Output Voltage



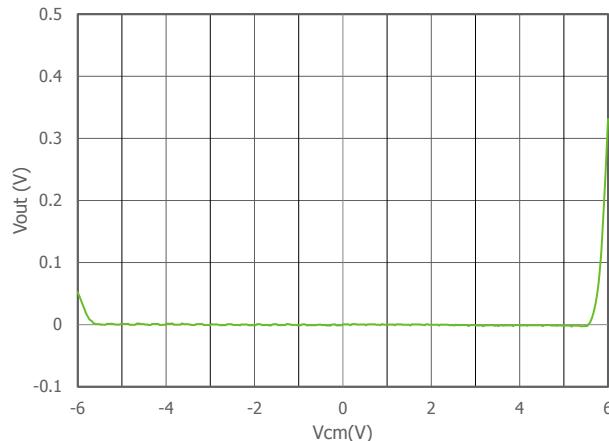
## Typical Performance Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$ ,  $G = 2$ ; unless otherwise noted.

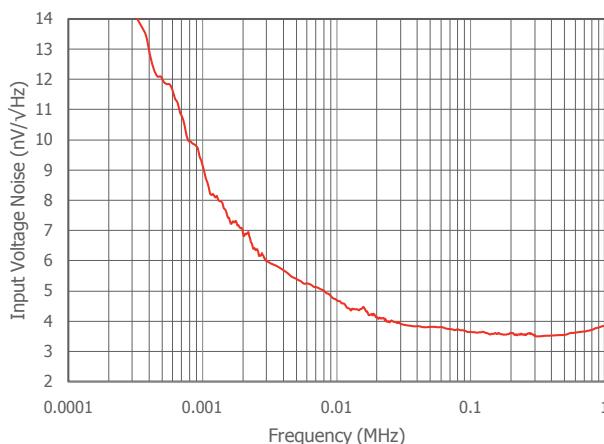
### Open Loop Gain and Phase vs.



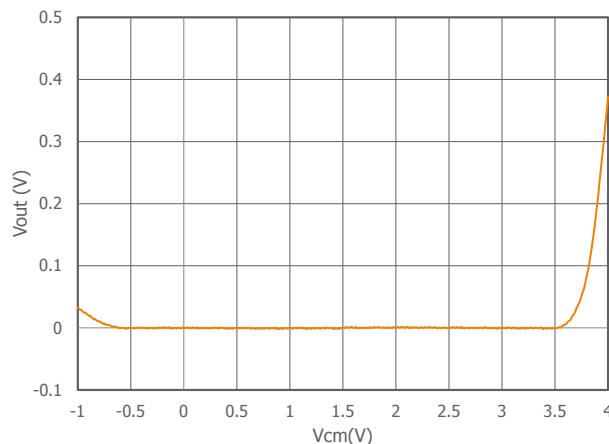
### CMIR



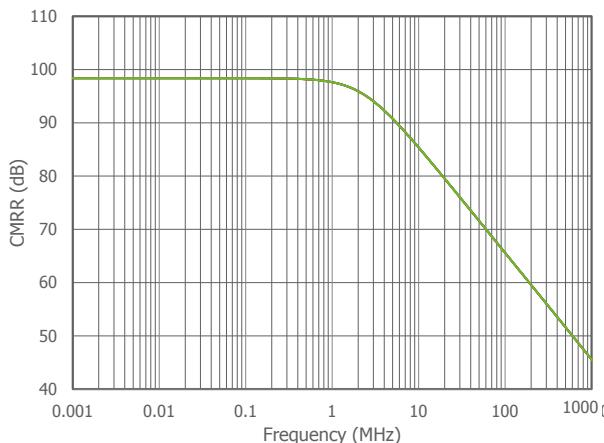
### Input Voltage Noise



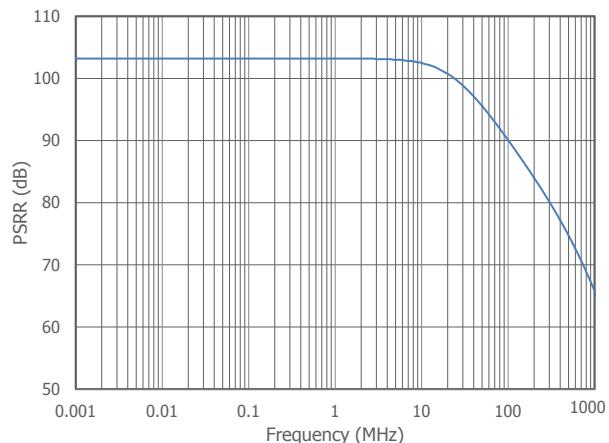
### CMIR at $V_S = 3\text{V}$



### CMRR vs. Frequency



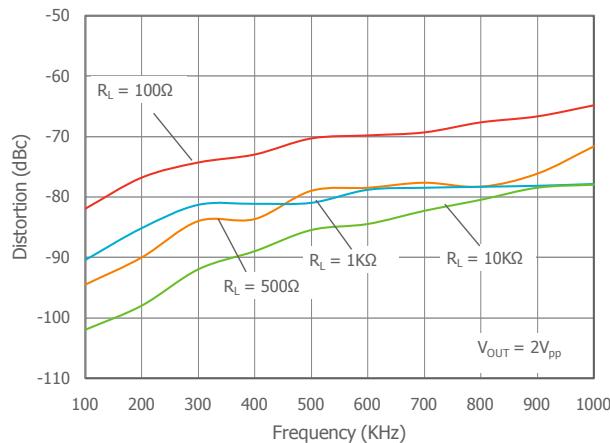
### PSRR vs. Frequency



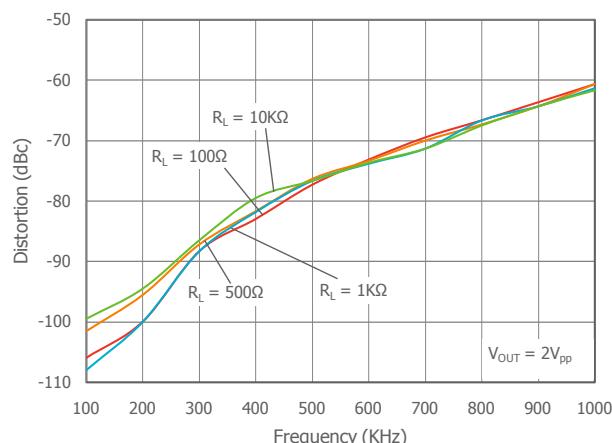
## Typical Performance Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$ ,  $G = 2$ ; unless otherwise noted.

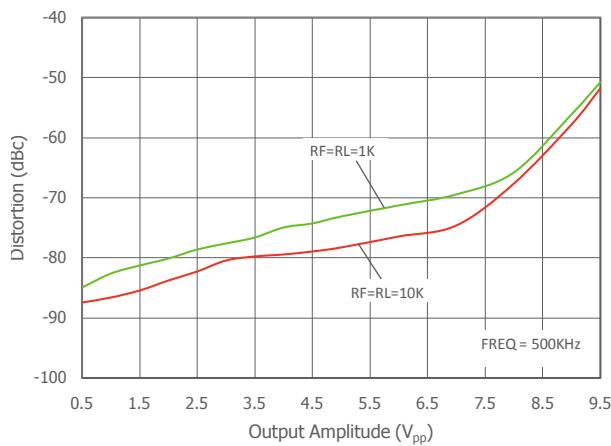
2nd Harmonic Distortion vs.  $R_L$



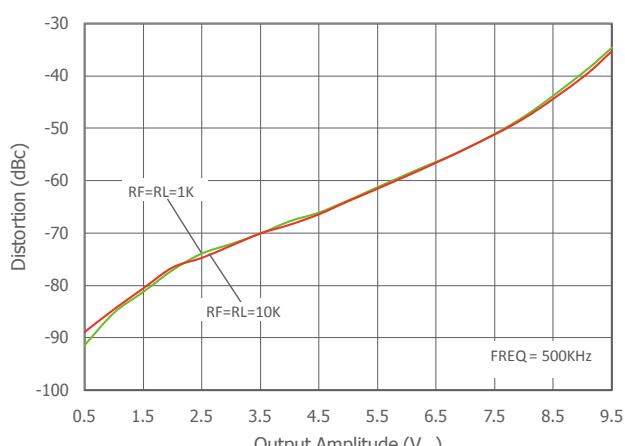
3rd Harmonic Distortion vs.  $R_L$



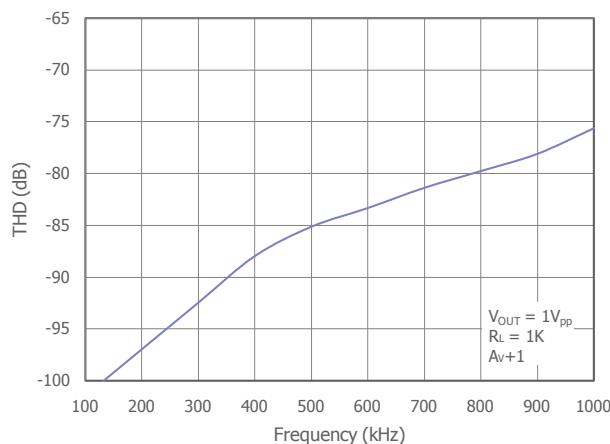
2nd Harmonic Distortion vs.  $V_{\text{OUT}}$



3rd Harmonic Distortion vs.  $V_{\text{OUT}}$



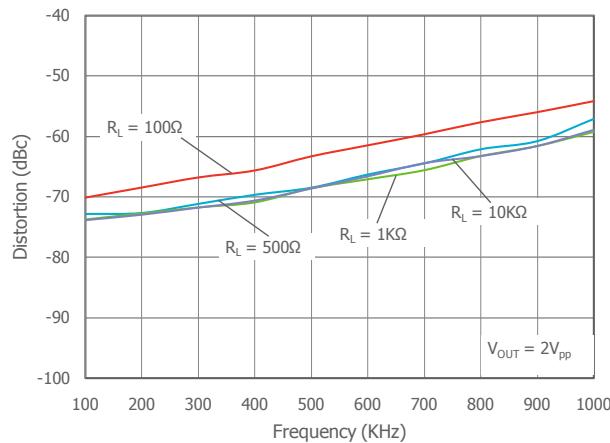
THD vs. Frequency



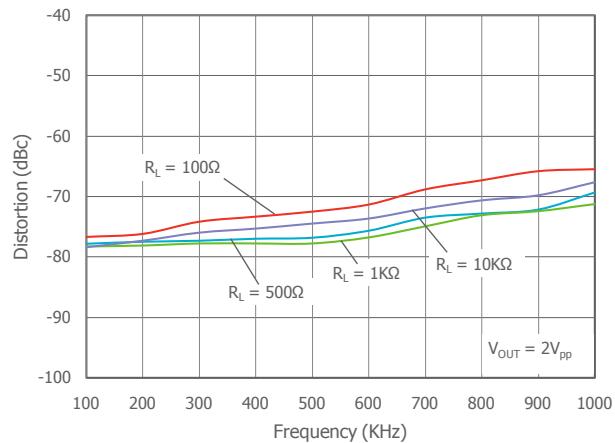
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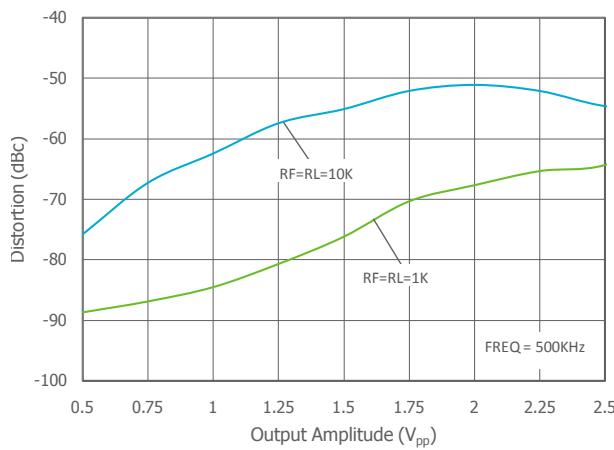
2nd Harmonic Distortion vs.  $R_L$  at  $V_S = 3\text{V}$



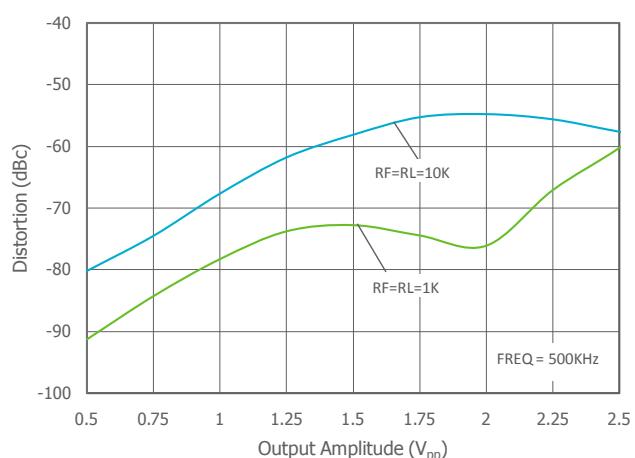
3rd Harmonic Distortion vs.  $R_L$  at  $V_S = 3\text{V}$



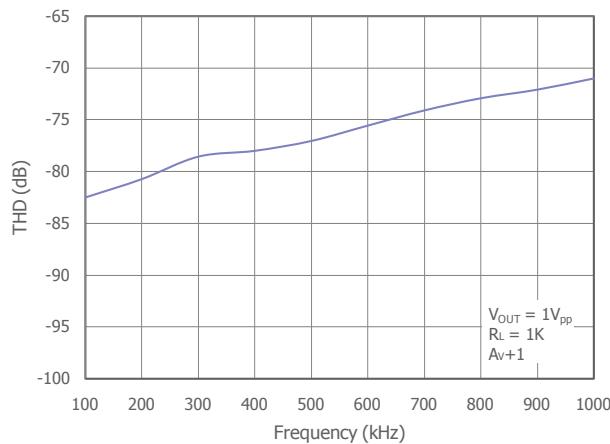
2nd Harmonic Distortion vs.  $V_{\text{OUT}}$  at  $V_S = 3\text{V}$



3rd Harmonic Distortion vs.  $V_{\text{OUT}}$  at  $V_S = 3\text{V}$



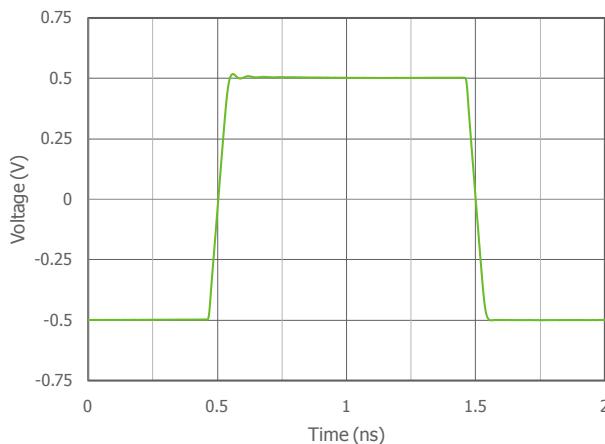
THD vs. Frequency at  $V_S = 3\text{V}$



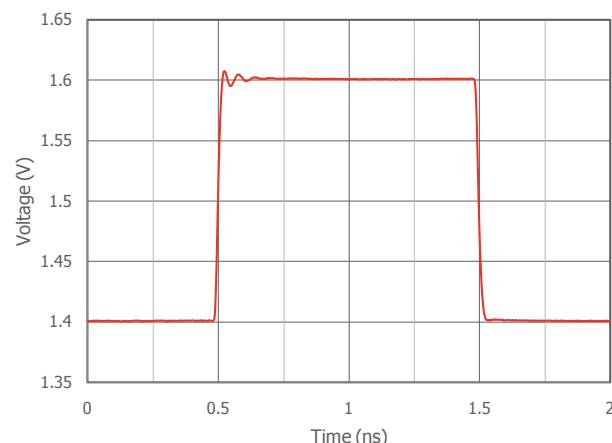
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$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{V}$ ,  $R_f = 1\text{k}\Omega$ ,  $R_L = 1\text{k}\Omega$ ,  $G = 2$ ; unless otherwise noted.

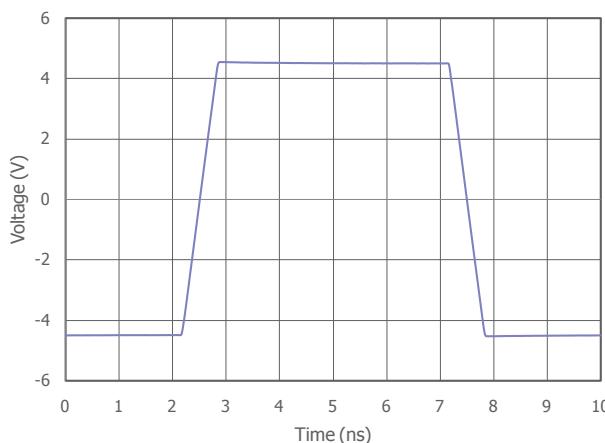
Small Signal Pulse Response



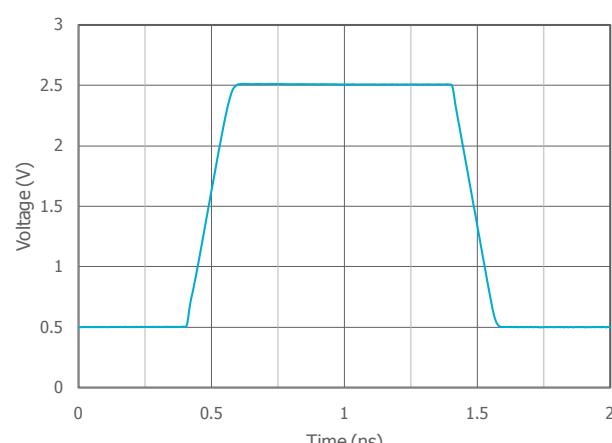
Small Signal Pulse Response at  $V_S = 3\text{V}$



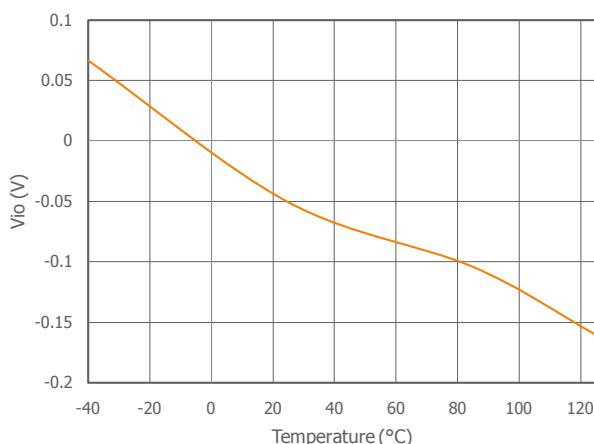
Large Signal Pulse Response



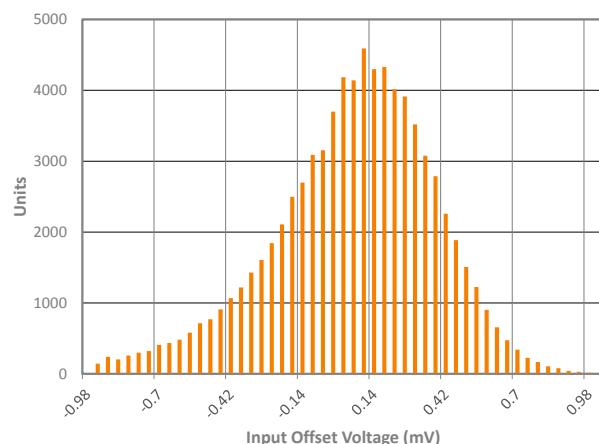
Large Signal Pulse Response at  $V_S = 3\text{V}$



Input Offset Voltage vs. Temperature



Input Offset Voltage Distribution



## Application Information

### Basic Information

Figures 1 and 2 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations.

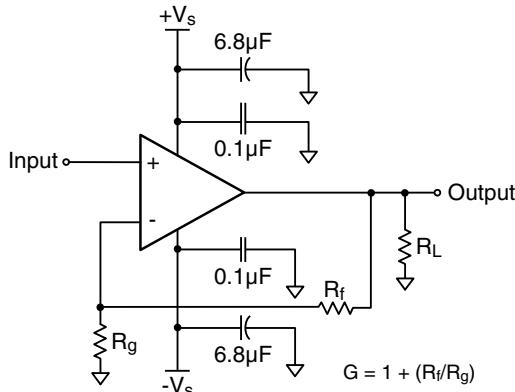


Figure 1: Typical Non-Inverting Gain Circuit

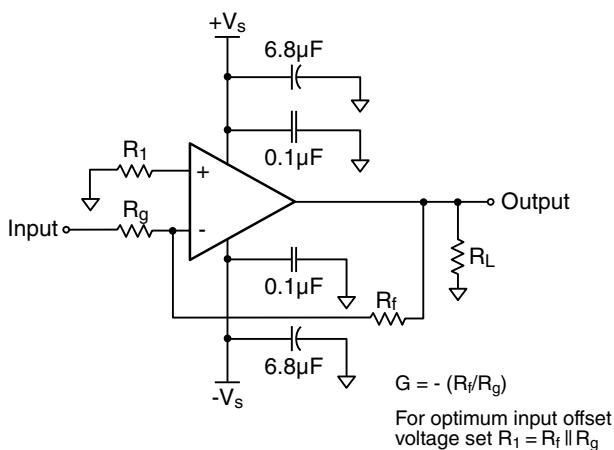


Figure 2: Typical Inverting Gain Circuit

### Power Dissipation

Power dissipation should not be a factor when operating under the stated  $500\Omega$  load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond its intended operating range.

Maximum power levels are set by the absolute maximum junction rating of  $150^\circ\text{C}$ . To calculate the junction temperature, the package thermal resistance value  $\Theta_{\text{JA}}$  ( $\Theta_{\text{JA}}$ ) is used along with the total die power dissipation.

$$T_{\text{Junction}} = T_{\text{Ambient}} + (\Theta_{\text{JA}} \times P_D)$$

Where  $T_{\text{Ambient}}$  is the temperature of the working environment.

In order to determine  $P_D$ , the power dissipated in the load needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{\text{supply}} - P_{\text{load}}$$

Supply power is calculated by the standard power equation.

$$P_{\text{supply}} = V_{\text{supply}} \times I_{\text{RMS supply}}$$

$$V_{\text{supply}} = V_{S+} - V_{S-}$$

Power delivered to a purely resistive load is:

$$P_{\text{load}} = ((V_{\text{load}})_{\text{RMS}})^2 / R_{\text{load eff}}$$

The effective load resistor ( $R_{\text{load eff}}$ ) will need to include the effect of the feedback network. For instance,

$R_{\text{load eff}}$  in Figure 2 would be calculated as:

$$R_L \parallel (R_f + R_g)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load impedance is needed to determine the dissipated power. Here,  $P_D$  can be found from

$$P_D = P_{\text{Quiescent}} + P_{\text{Dynamic}} - P_{\text{load}}$$

Quiescent power can be derived from the specified  $I_S$  values along with known supply voltage,  $V_{\text{supply}}$ . Load power can be calculated as above with the desired signal amplitudes using:

$$(V_{\text{load}})_{\text{RMS}} = V_{\text{peak}} / \sqrt{2}$$

$$(I_{\text{load}})_{\text{RMS}} = (V_{\text{load}})_{\text{RMS}} / R_{\text{load eff}}$$

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

$$P_{\text{Dynamic}} = (V_{S+} - V_{\text{load}})_{\text{RMS}} \times (I_{\text{load}})_{\text{RMS}}$$

Assuming the load is referenced in the middle of the power rails or  $V_{\text{supply}}/2$ .

Figure 3 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

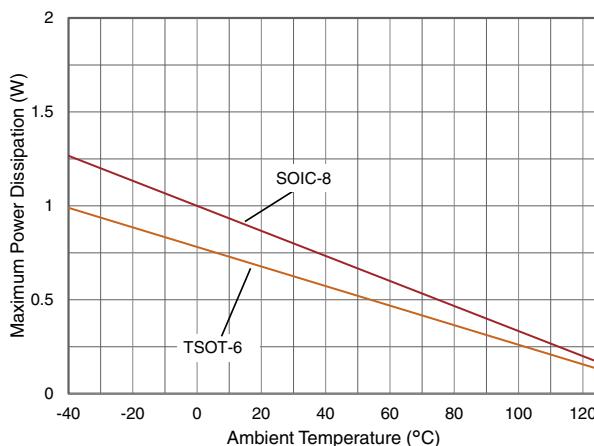
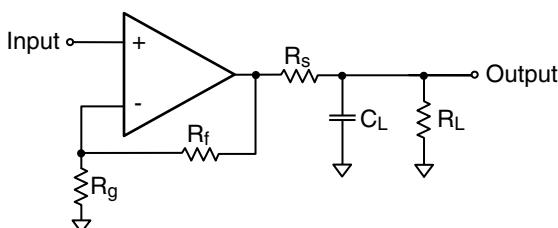


Figure 3. Maximum Power Derating

### Driving Capacitive Loads

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance,  $R_S$ , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 4.

Figure 4. Addition of  $R_S$  for Driving Capacitive Loads

The CLC1003 is capable of driving up to 300pF directly, with no series resistance. Directly driving 500pF causes over 4dB of frequency peaking, as shown in the plot on page 6. Table 1 provides the recommended  $R_S$  for various capacitive loads. The recommended  $R_S$  values result in  $\leq 1$ dB peaking in the frequency response. The Frequency Response vs.  $C_L$  plots, on page 6, illustrate the response of the CLC1003.

$C_L$ (pF)	$R_S$ ( $\Omega$ )	-3dB BW (MHz)
500	10	27
1000	7.5	20
3000	4	15

Table 1: Recommended  $R_S$  vs.  $C_L$ 

For a given load capacitance, adjust  $R_S$  to optimize the tradeoff between settling time and bandwidth. In general, reducing  $R_S$  will increase bandwidth at the expense of additional overshoot and ringing.

### Overdrive Recovery

An overdrive condition is defined as the point when either one of the inputs or the output exceed their specified voltage range. Overdrive recovery is the time needed for the amplifier to return to its normal or linear operating point. The recovery time varies based on whether the input or output is overdriven and by how much the ranges are exceeded. The CLC1003 will typically recover in less than 20ns from an overdrive condition. Figure 5 shows the CLC1003 in an overdriven condition.

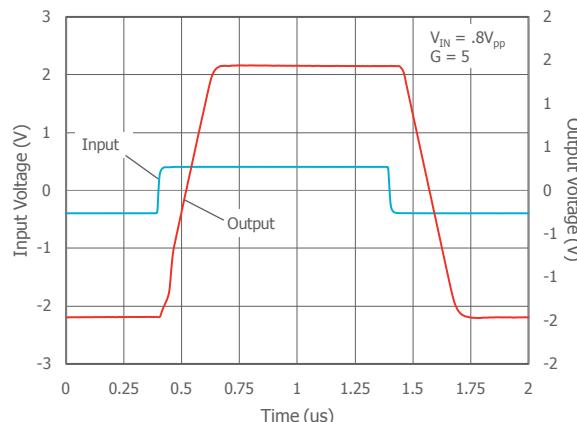


Figure 5: Overdrive Recovery

### Considerations for Offset and Noise Performance

#### Offset Analysis

There are three sources of offset contribution to consider; input bias current, input bias current mismatch, and input offset voltage. The input bias currents are assumed to be equal with an additional offset current in one of the inputs to account for mismatch. The bias currents will not affect the offset as long as the parallel combination of  $R_f$  and  $R_g$  matches  $R_t$ . Refer to Figure 6.

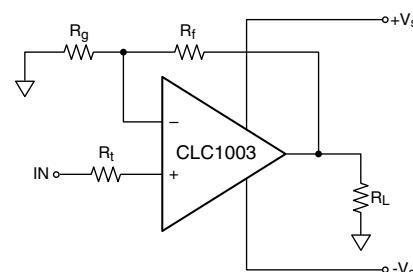


Figure 6: Circuit for Evaluating Offset

The first place to start is to determine the source resistance. If it is very small an additional resistance may need to be added to keep the values of  $R_f$  and  $R_g$  to practical levels. For this analysis we assume that  $R_t$  is the total resistance present on the non-inverting input. This gives us one equation that we must solve:

$$R_t = R_g \parallel R_f$$

This equation can be rearranged to solve for  $R_g$ :

$$R_g = (R_t * R_f) / (R_f - R_t)$$

The other consideration is desired gain (G) which is:

$$G = (1 + R_f/R_g)$$

By plugging in the value for  $R_g$  we get

$$R_f = G * R_t$$

And  $R_g$  can be written in terms of  $R_t$  and G as follows:

$$R_g = (G * R_t) / (G - 1)$$

The complete input offset equation is now only dependent on the voltage offset and input offset terms given by:

$$VI_{OS} = \sqrt{(V_{IO})^2 + (I_{OS} * RT)^2}$$

And the output offset is:

$$VO_{OS} = G * \sqrt{(V_{IO})^2 + (I_{OS} * RT)^2}$$

## Noise analysis

The complete equivalent noise circuit is shown in Figure 7.

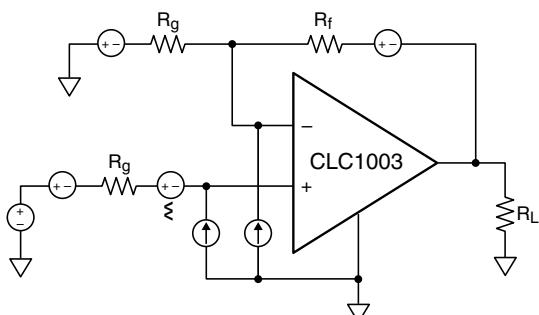


Figure 7: Complete Equivalent Noise Circuit

The complete noise equation is given by:

$$v_o^2 = v_{orext}^2 + \left( e_n \left( 1 + \frac{RF}{RG} \right) \right)^2 + \left( i_{bp} * RT \left( 1 + \frac{RF}{RG} \right) \right)^2 + \left( i_{bn} * RF \right)^2$$

Where  $V_{orext}$  is the noise due to the external resistors and is given by:

$$v_o^2 = \left( e_n \left( 1 + \frac{RF}{RG} \right) \right)^2 + \left( e_G * \frac{RF}{RG} \right)^2 + e_F^2$$

The complete equation can be simplified to:

$$v_o^2 = 3 * (4kT * G * RT) + (e_n G)^2 + 2 * (i_n * RT)^2$$

It's easy to see that the effect of amplifier voltage noise is proportionate to gain and will tend to dominate at large gains. The other terms will have their greatest impact at large  $R_t$  values at lower gains.

## Layout Considerations

General layout and supply bypassing play major roles in high frequency performance. Exar has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8 $\mu$ F and 0.1 $\mu$ F ceramic capacitors for power supply decoupling
- Place the 6.8 $\mu$ F capacitor within 0.75 inches of the power pin
- Place the 0.1 $\mu$ F capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

## Evaluation Board Information

The following evaluation boards are available to aid in the testing and layout of these devices:

Evaluation Board #	Products
CEB002	CLC1003 in TSOT
CEB003	CLC1003 in SOIC

## Evaluation Board Schematics

Evaluation board schematics and layouts are shown in Figures 8-12. These evaluation boards are built for dual-supply operation. Follow these steps to use the board in a single-supply application:

1. Short  $-V_S$  to ground.
2. Use C3 and C4, if the  $-V_S$  pin of the amplifier is not directly connected to the ground plane.

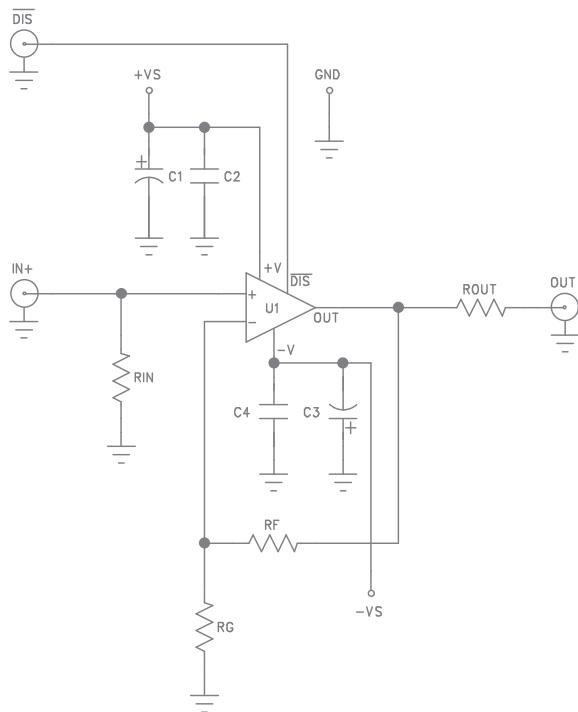


Figure 8. CEB002 &amp; CEB003 Schematic

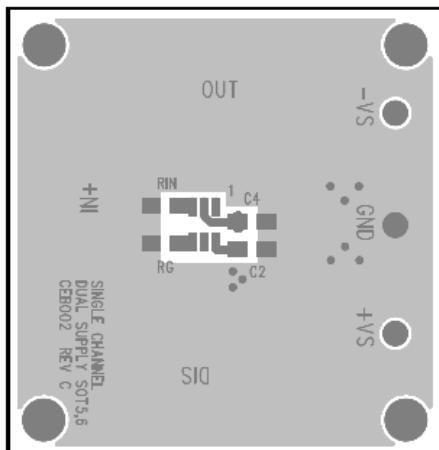


Figure 9. CEB002 Top View

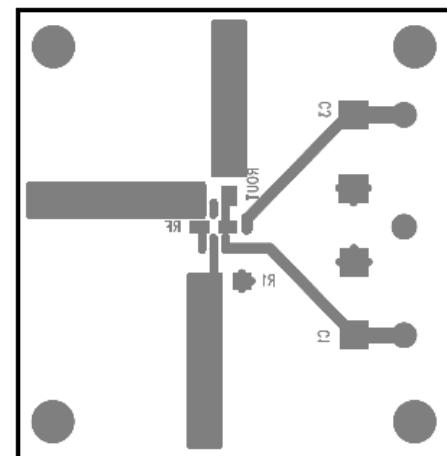


Figure 10. CEB002 Bottom View

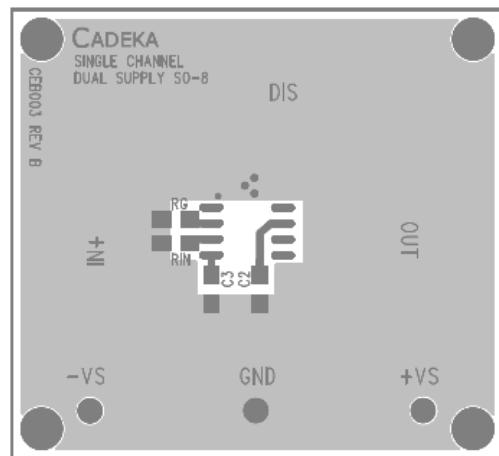


Figure 11. CEB003 Top View

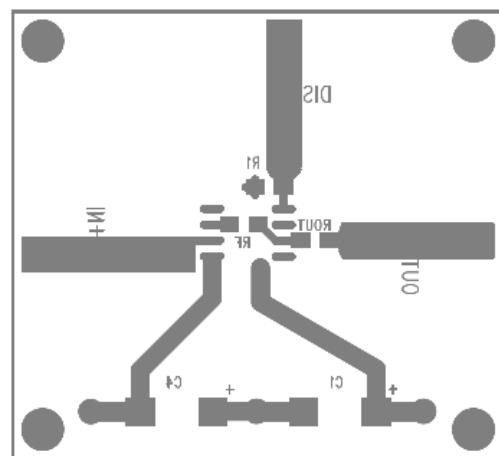
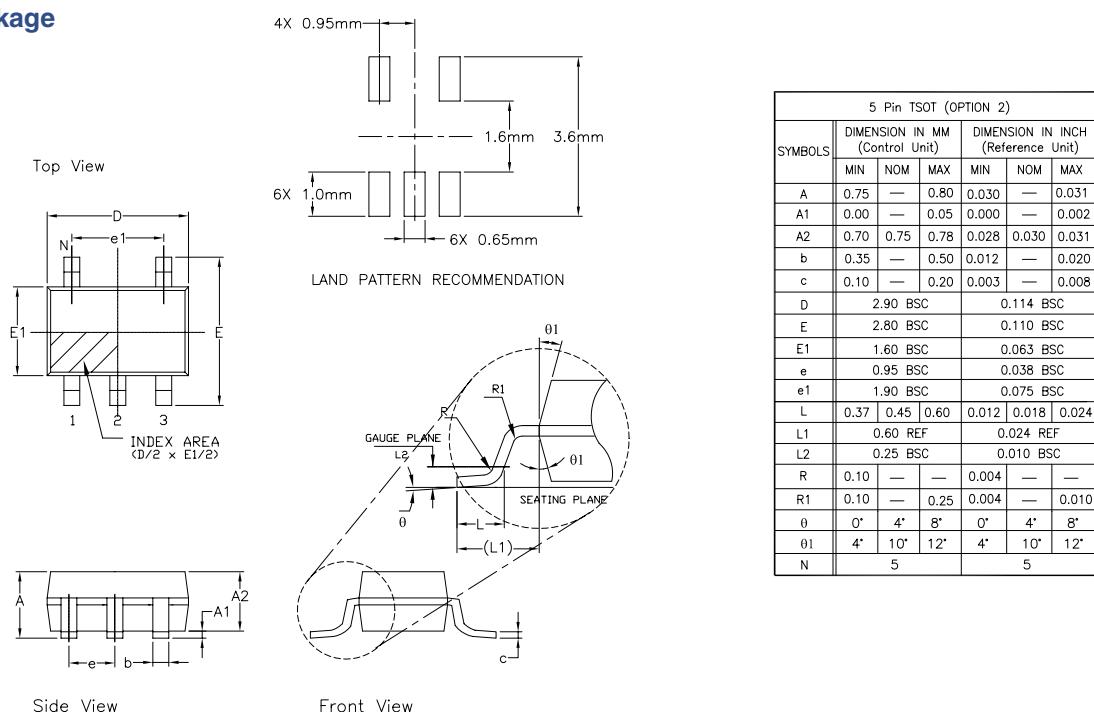


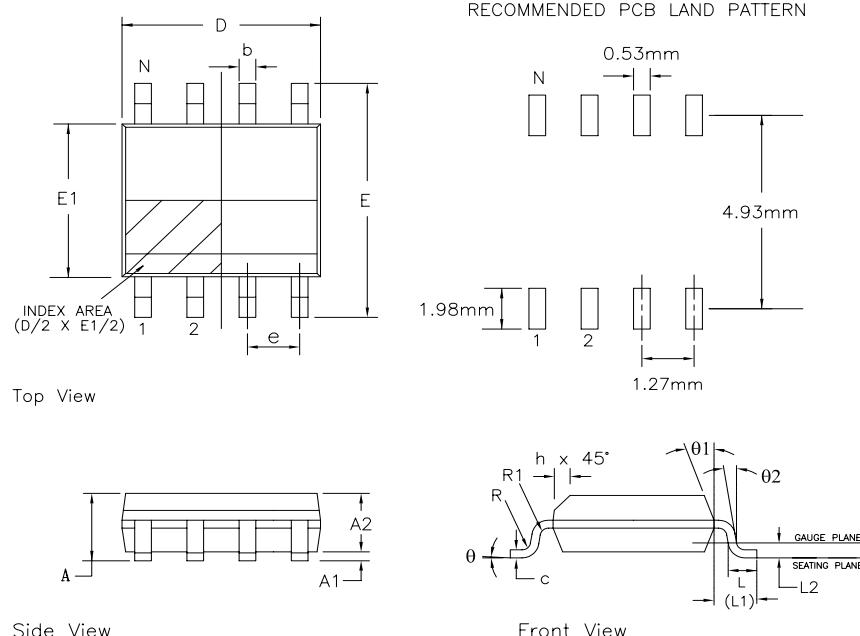
Figure 12. CEB003 Bottom View

## Mechanical Dimensions

### TSOT-5 Package



### SOIC-8 Package



SYMBOLS	DIMENSIONS IN MM (Control Unit)			DIMENSIONS IN INCH (Reference Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35	—	1.75	0.053	—	0.069
A1	0.10	—	0.25	0.004	—	0.010
A2	1.25	—	1.65	0.049	—	0.065
b	0.31	—	0.51	0.012	—	0.020
c	0.17	—	0.25	0.007	—	0.010
E	6.00	BSC	—	0.236	BSC	—
E1	3.90	BSC	—	0.154	BSC	—
e	1.27	BSC	—	0.050	BSC	—
h	0.25	—	0.50	0.010	—	0.020
L	0.40	—	1.27	0.010	—	0.050
L1	1.04	REF	—	0.041	REF	—
L2	0.25	BSC	—	0.010	BSC	—
R	0.07	—	—	0.003	—	—
R1	0.07	—	—	0.003	—	—
θ	0°	—	8°	0°	—	8°
01	5°	—	15°	5°	—	15°
02	0°	—	—	0°	—	—
D	4.90	BSC	—	0.193	BSC	—
N	8		8			

## Ordering Information

Part Number	Package	Green	Operating Temperature Range	Packaging Quantity
CLC1003 Ordering Information				
CLC1003IST5X	TSOT-5	Yes	-40°C to +125°C	2.5k Tape & Reel
CLC1003IST5MTR	TSOT-5	Yes	-40°C to +125°C	250 Tape & Reel
CLC1003IST5EVB	Evaluation Board	N/A	N/A	N/A
CLC1003ISO8X	SOIC-8	Yes	-40°C to +125°C	2.5k Tape & Reel
CLC1003ISO8MTR	SOIC-8	Yes	-40°C to +125°C	250 Tape & Reel
CLC1003ISO8EVB	Evaluation Board	N/A	N/A	N/A

Moisture sensitivity level for all parts is MSL-1.

## Revision History

Revision	Date	Description
1D (ECN 1441-07)	September 2014	Reformat into Exar data sheet template. Updated ordering information table to include MTR and EVB part numbers. Increased "I" temperature range from +85 to +125°C. Removed "A" temp grade parts, since "I" is now equivalent. Updated thermal resistance numbers and package outline drawings.

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